

SEVENTEENTH ANNUAL

BiTS

TM

Burn-in & Test Strategies Workshop

March 6 - 9, 2016

**Hilton Phoenix / Mesa Hotel
Mesa, Arizona**

Archive- Session 4

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Session 4

Marc Mössinger
Session Chair

BiTS Workshop 2016 Schedule

Performance Day

Tuesday March 8 - 8:00 am

Frequently High

"High Speed BGA Sockets from a System Perspective"

Don Thompson - R&D Altanova

"A Solution of Test, Inspection and Evaluation for Blind Signal Waveform on a Board"

Tatsumi Watabe, Makoto Kawamura, Hiroyuki Yamakoshi - S.E.R. Corporation

"Device Packaging and How It Affects RF Performance"

Noureen Sajid, Jeff Sherry - Johnstech International

"Automotive Radar Test"

Jason Mroczkowski - Xcerra Corporation

A Solution of Test, Inspection and Evaluation for Blind Signal Waveform on a Board

**Tatsumi Watabe, Makoto Kawamura, &
Hiroyuki Yamakoshi
S.E.R. Corporation**



**2016 BiTS Workshop
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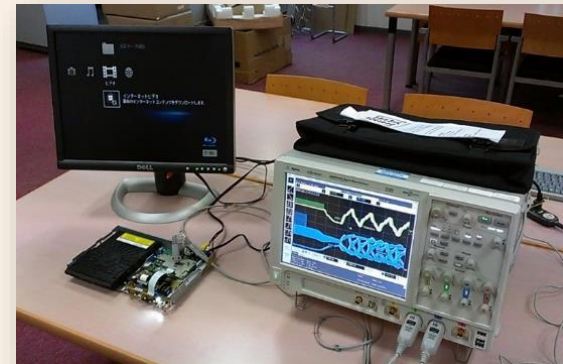


Purpose

- Blind signal waveform analysis on the system board by using **Signal Probe Socket**.

Conclusion

- Got a real signal waveform by introduction S-parameter data of signal probe socket and **InfiniiSim** performance.

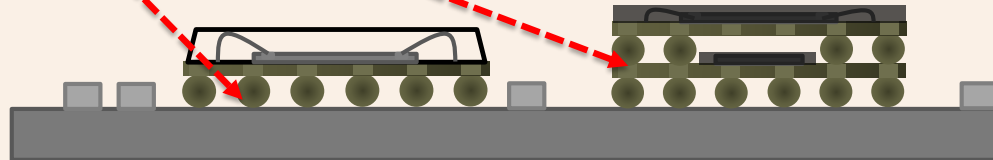
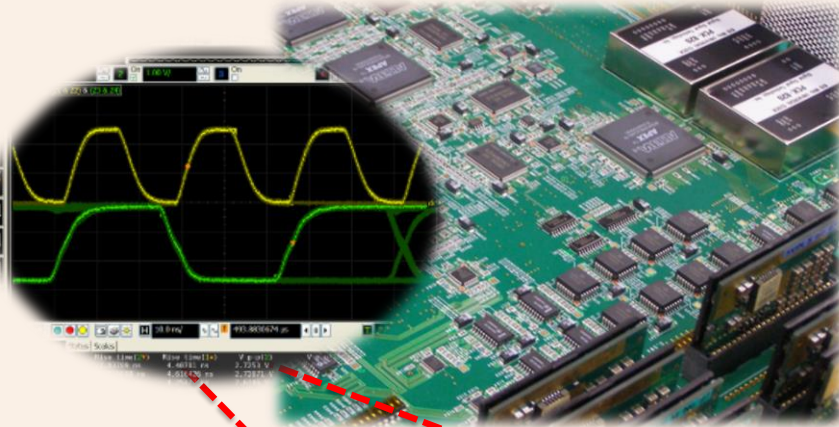


Agenda

- 1) What is a blind signal analysis?
- 2) Signal probe socket !
 - 2-1) YOROI ???
- 3) Blind signal measurement & data
- 4) Conclusion & summary

1) What is a blind signal analysis ?

Blind Signal !

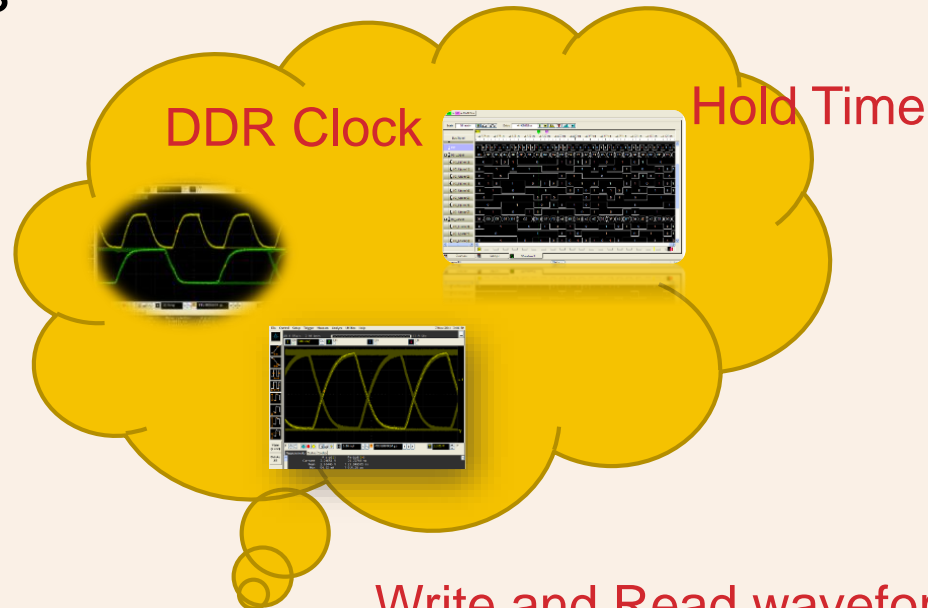


Blind signal analysis !

- Timing analysis between DDR and CPU.
- Measure and confirm a blind signal waveform directly underneath IC package.
- Define different approach for identification of a failure point when not re-appearance on LSI tester.
- Qualification of memory and CPU.
- Moving measurement point by using InfiniiSim.

Timing signal & waveform

Timing analysis
Verification
Quality control

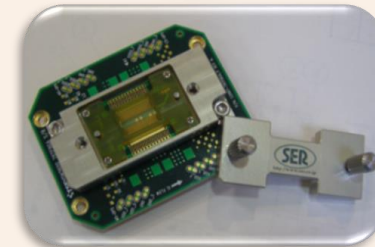
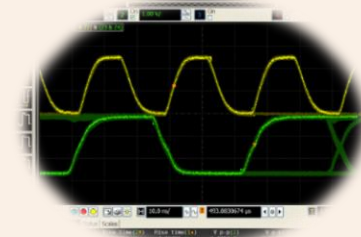
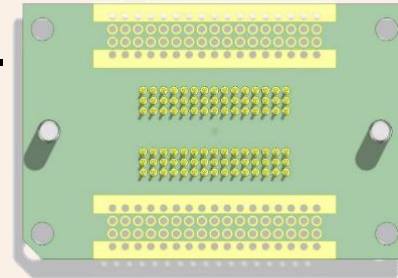


Write and Read waveform

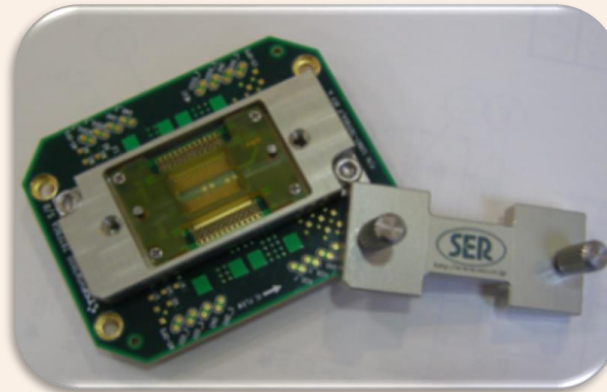
Set up Time

Blind signal measurement

1. **All signals** of 0.8mm pitch device should be accessible for measurement.
2. Support of **high-speed** signal measurements over 3.5 Gbps.
3. **Solderless mount.**
(Easy to replace the target IC)

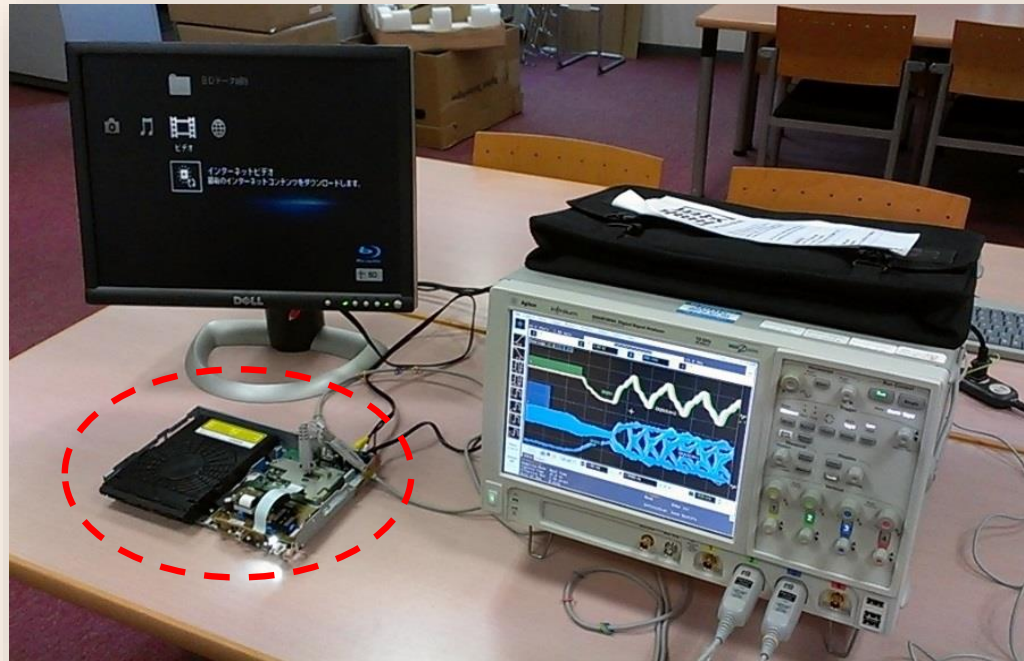


2) Signal Probe Socket !

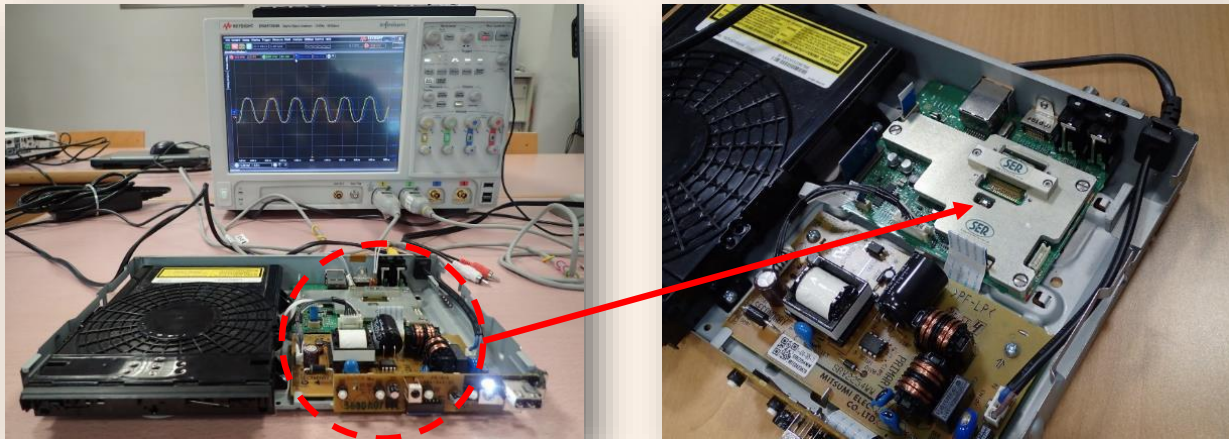


Blind signal probing

Signal measurement on DVD player



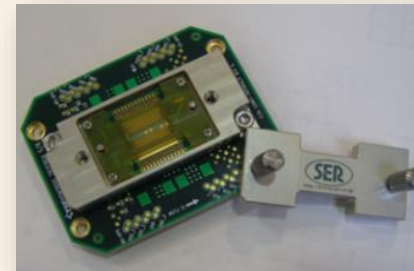
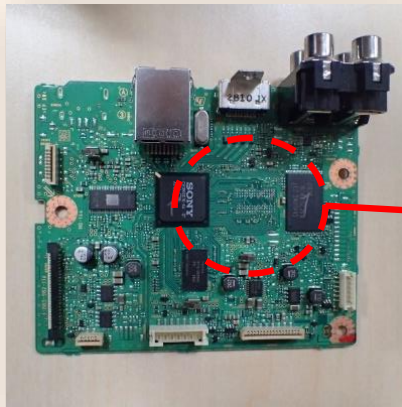
Blind signal probing



Signal probe socket is on a board of DVD player and connected to the oscilloscope.

Blind signal probing

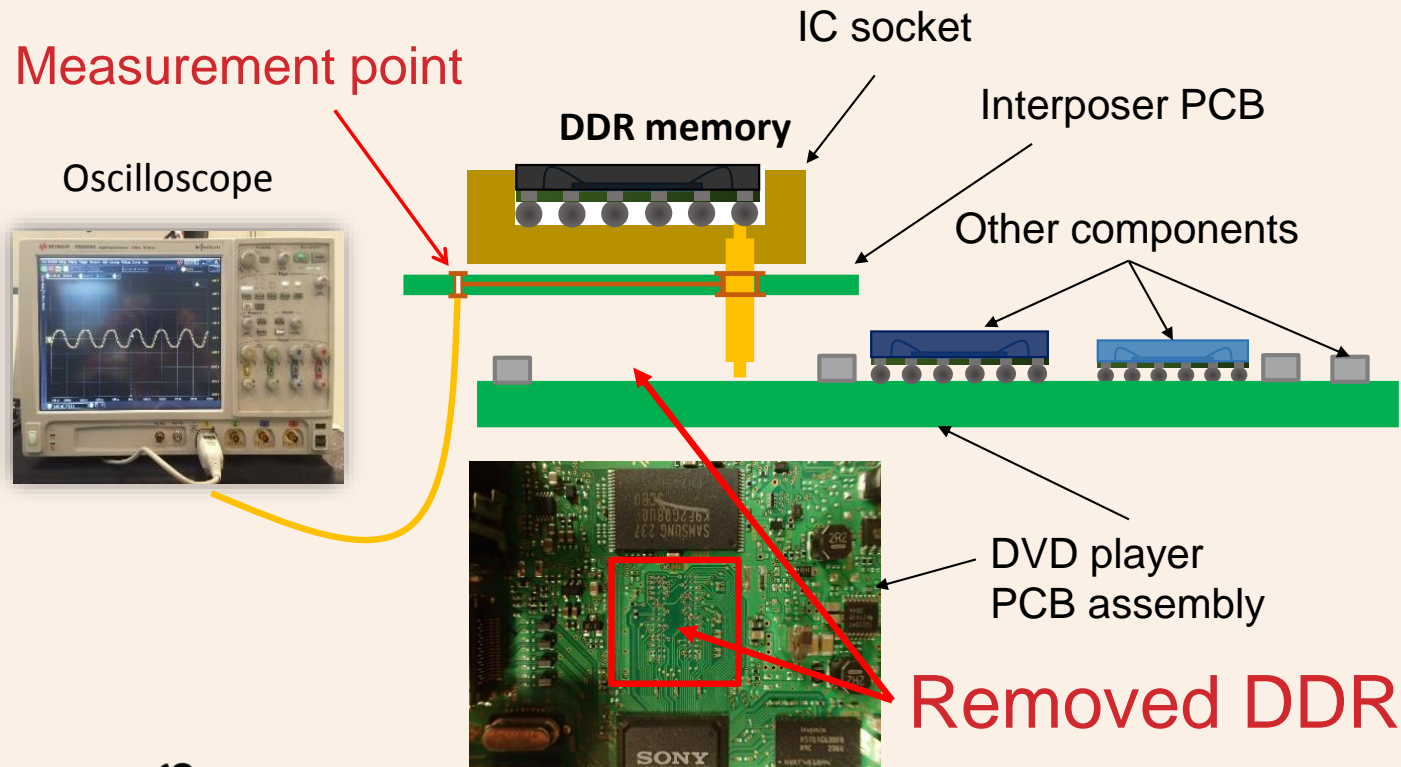
Removed DDR memory and mounted signal probe socket worn YOROI.



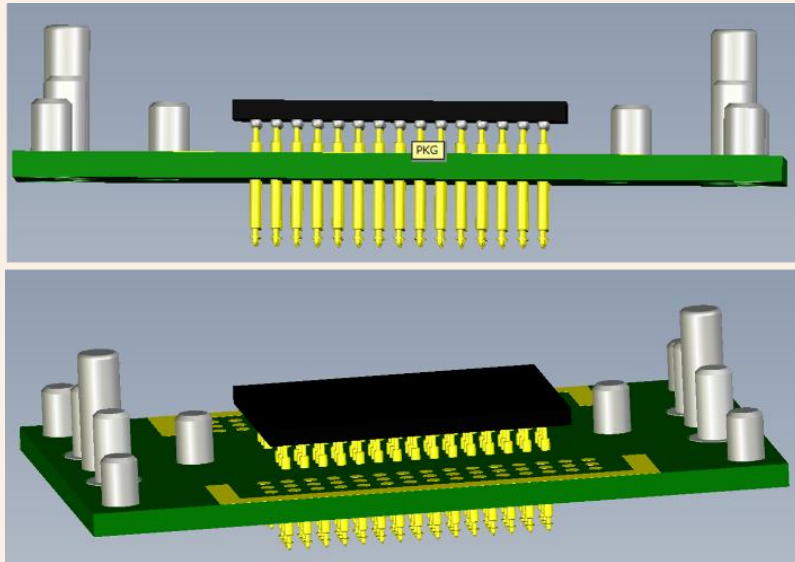
+



Setup for DDR memory's blind signal measurement



Signal probe socket basic structure

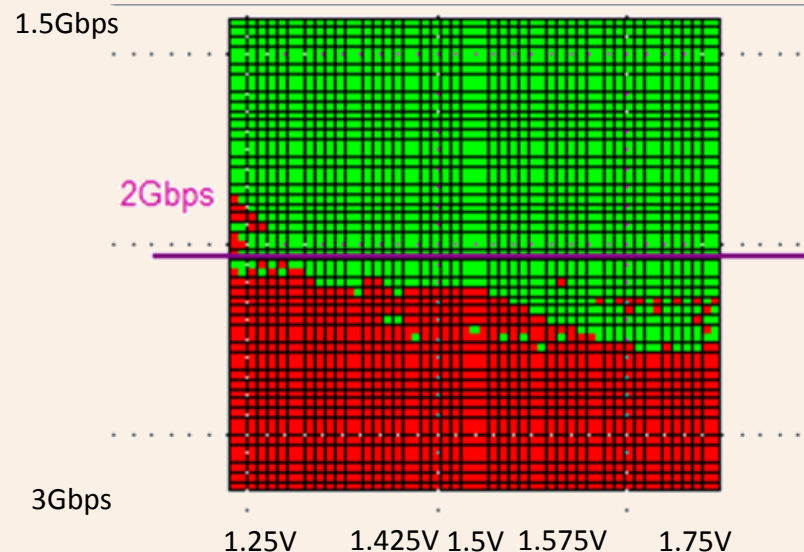


Example
PKG: BGA (DDR3 memory)
Pitch: 0.8mm
Pin count: 96 pin

Actual performance of DDR memory's signal probe socket

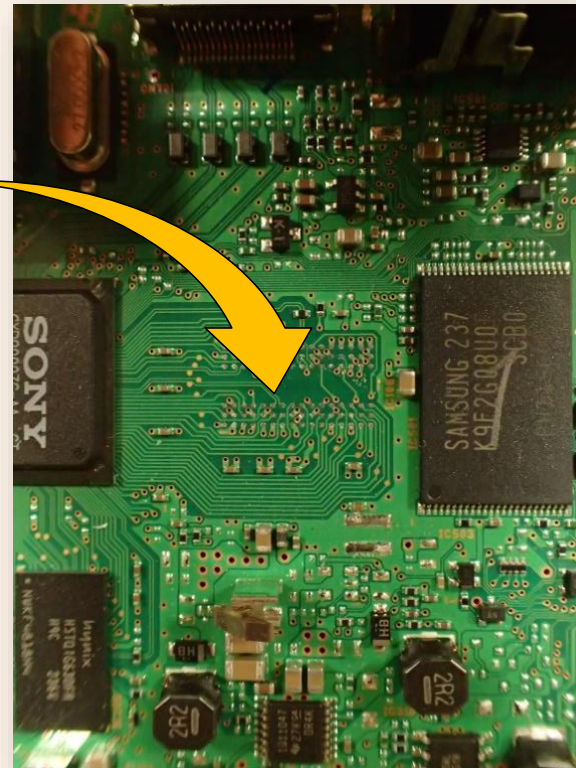
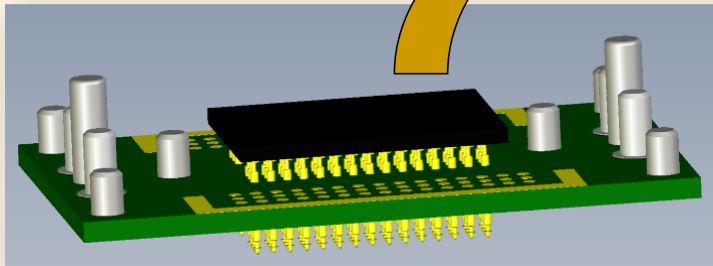
Shmoo plot analysis result

Tester
-Verigy
-V93000
-HSM3600



Blind signal probing design structure

YOROI structured mount is required for signal probe socket



2)-1 YOROI ???

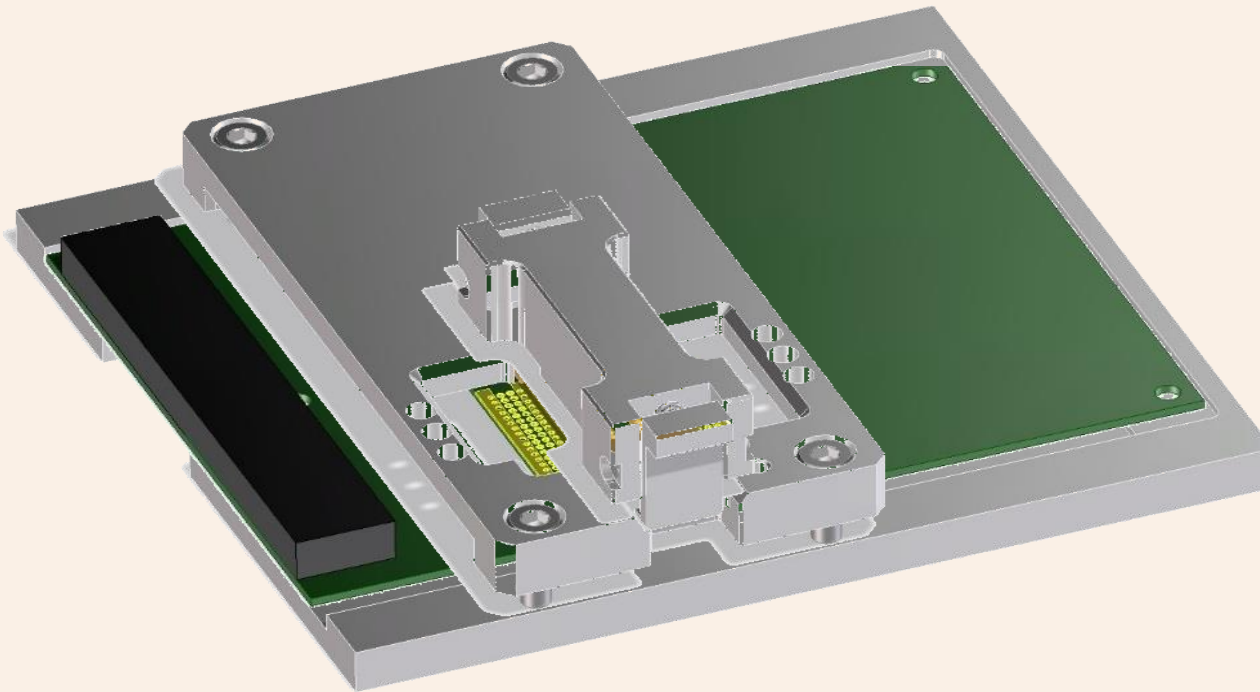
**SAMURAI wore
YOROI for fighting.**

And signal probe
socket also must be.

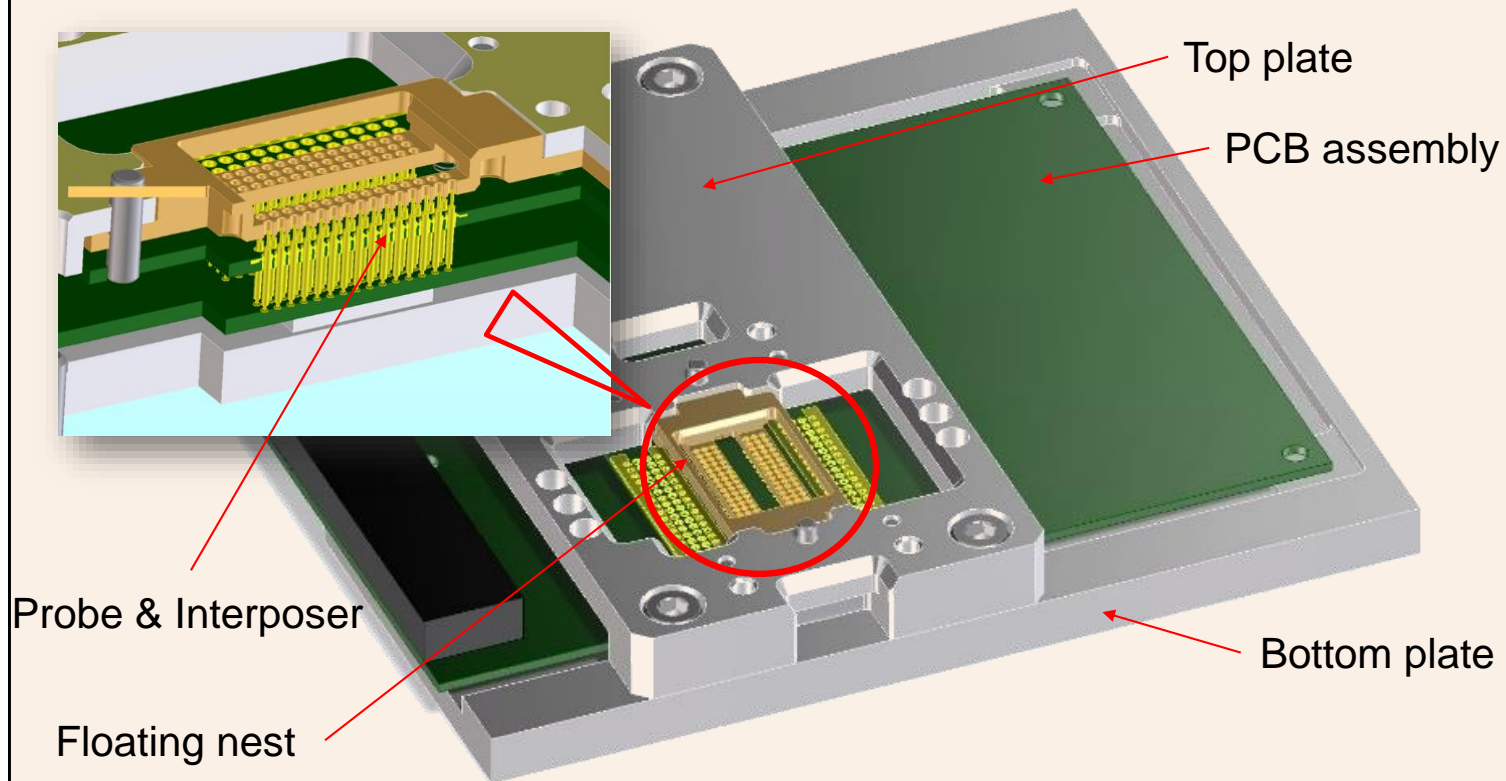
Why ?



YOROI structure for signal probe socket

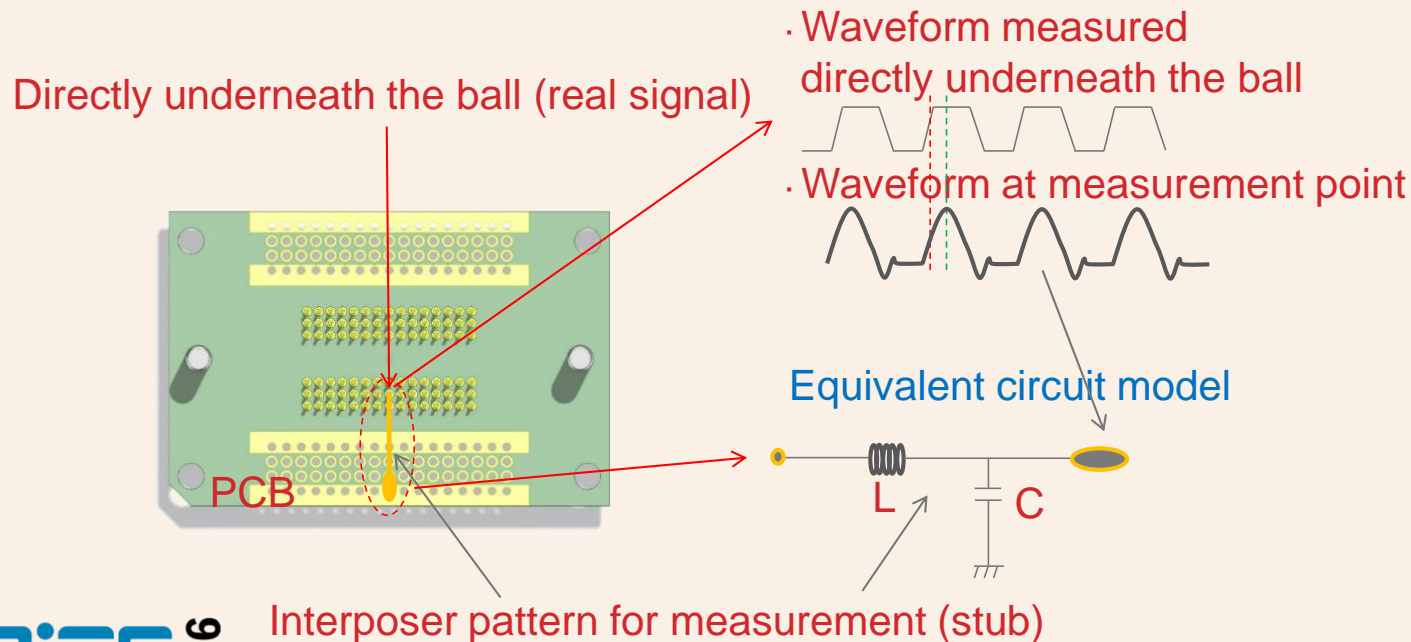


Signal probe socket worn YOROI

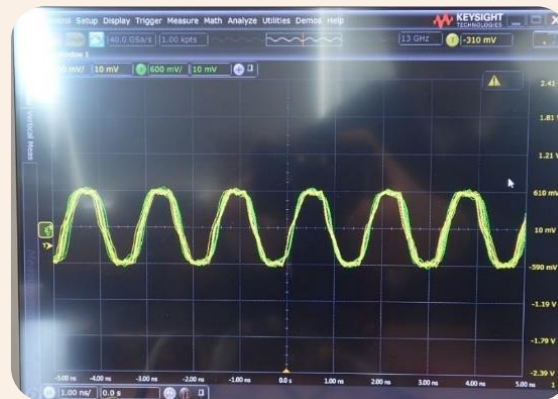


Interposer element

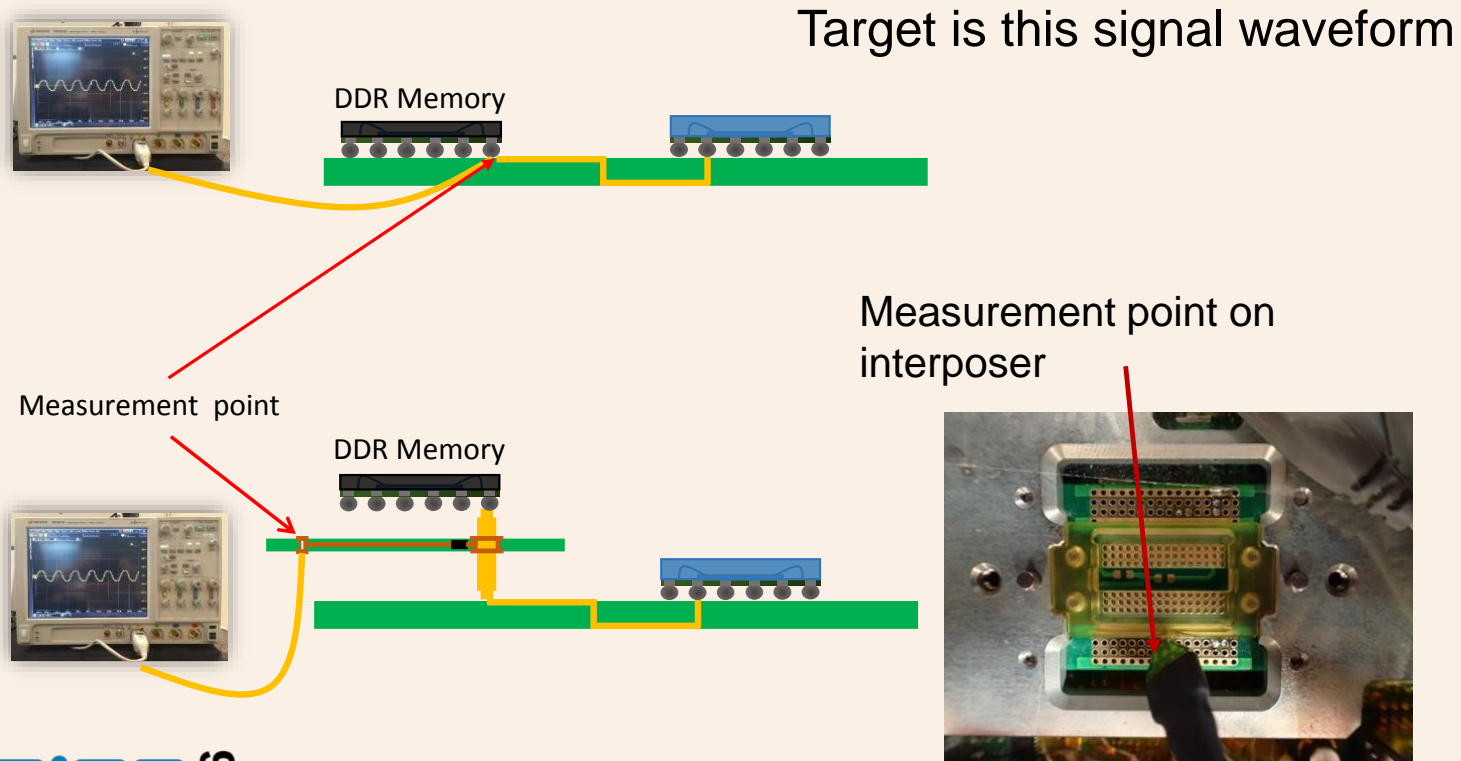
It influences the measurement of the blind signal waveform.



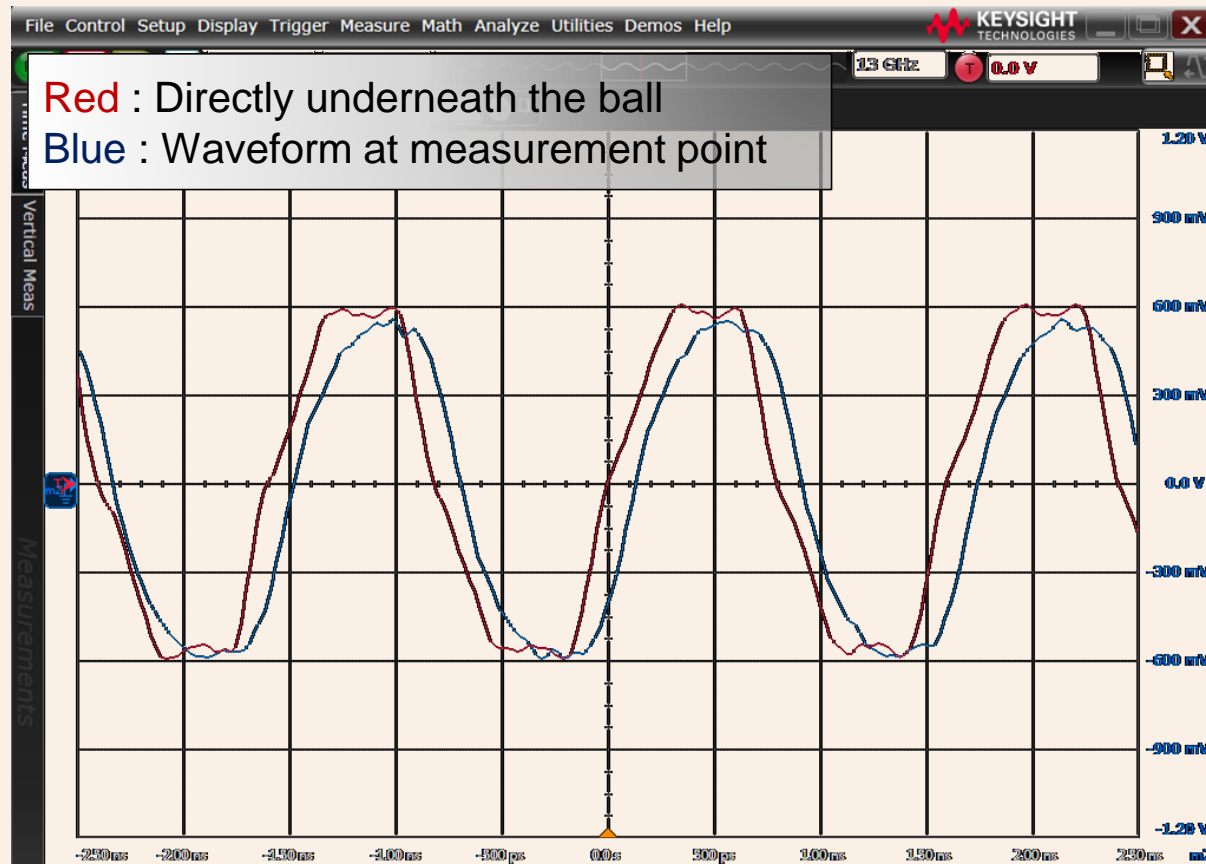
3) Blind signal measurement & data



Testing procedure & method



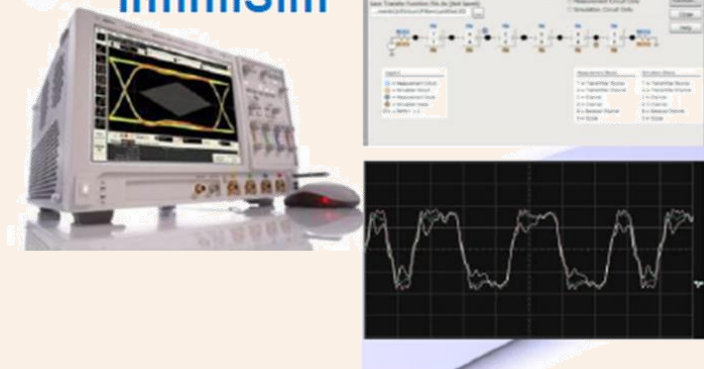
Actual DDR clock signal waveform



Waveform transformation

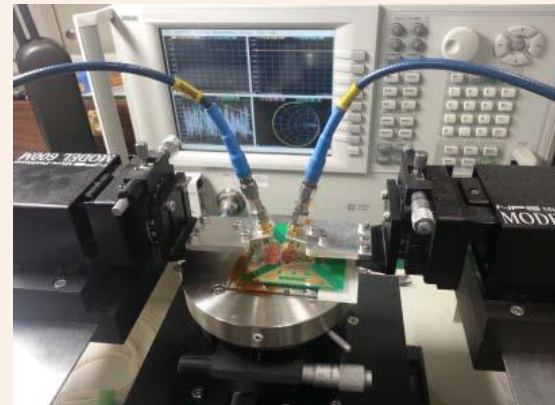
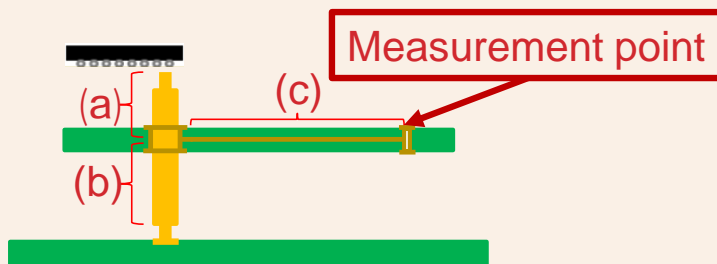
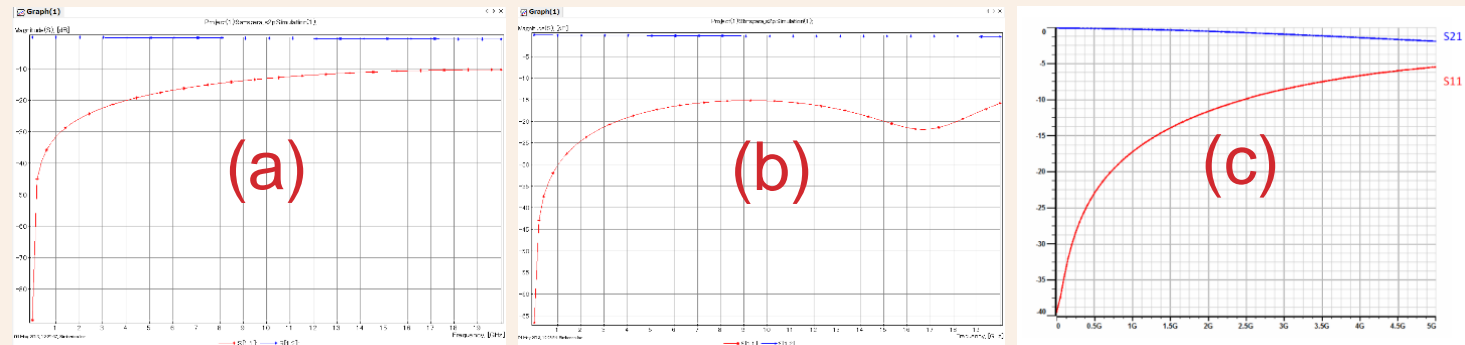
InfiniiSim by Keysight Technologies

Oscilloscope
InfiniiSim



S-parameters of signal probe socket

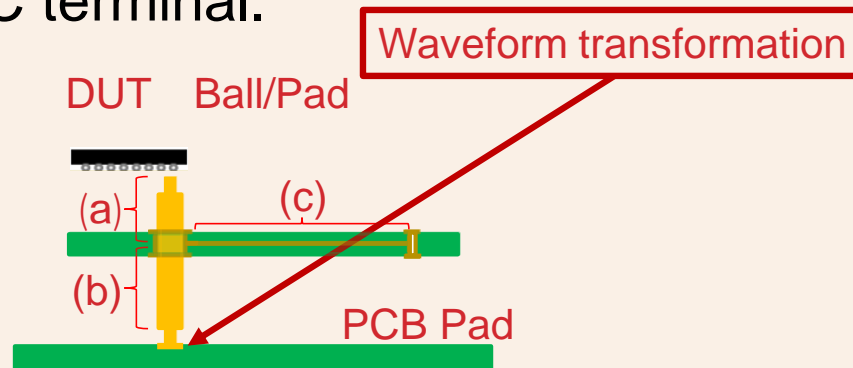
Actual S-parameter data of signal probe socket



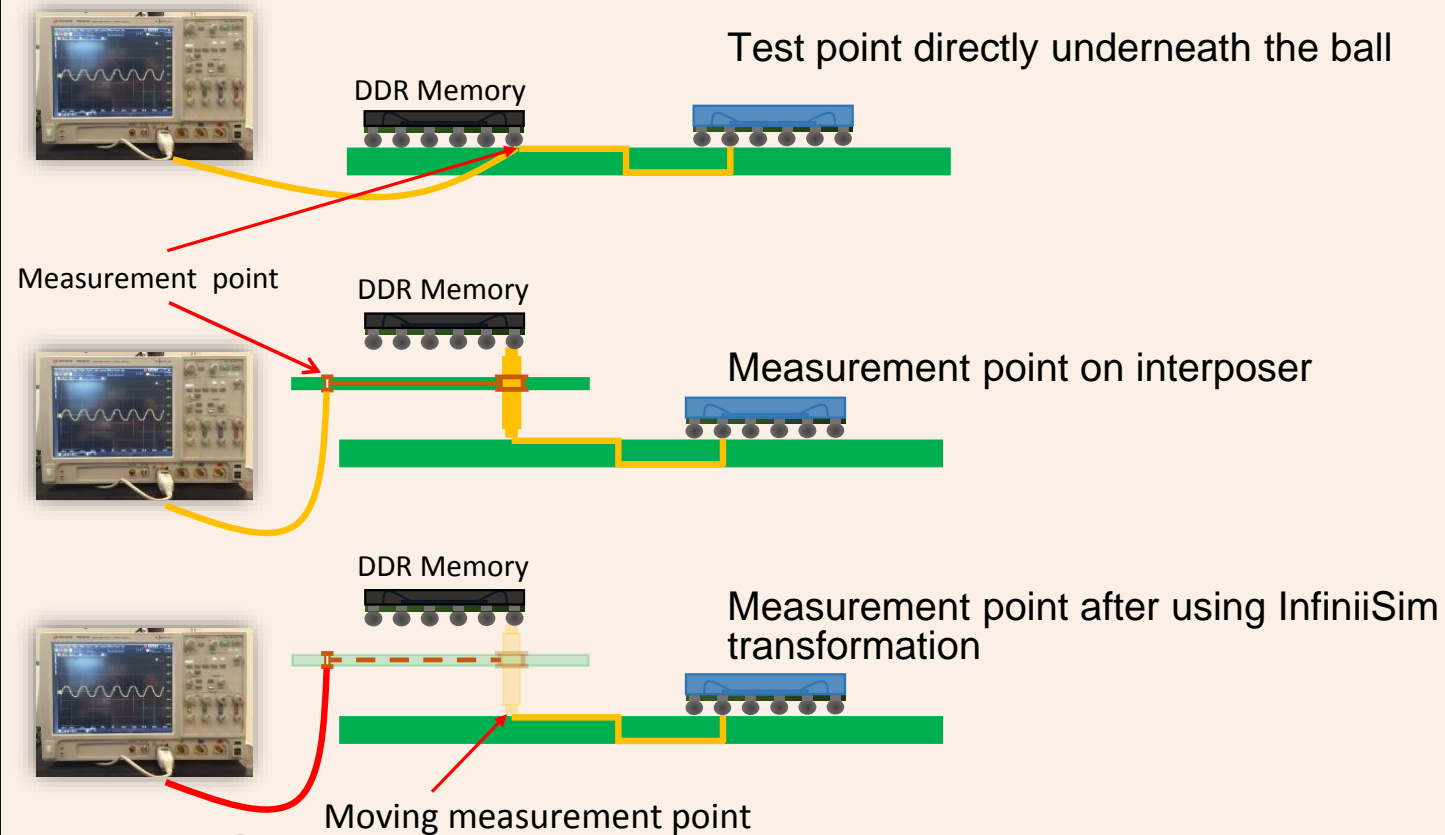
Waveform transformation

Measurement point waveform includes all S-parametric data of (a),(b) and (c)

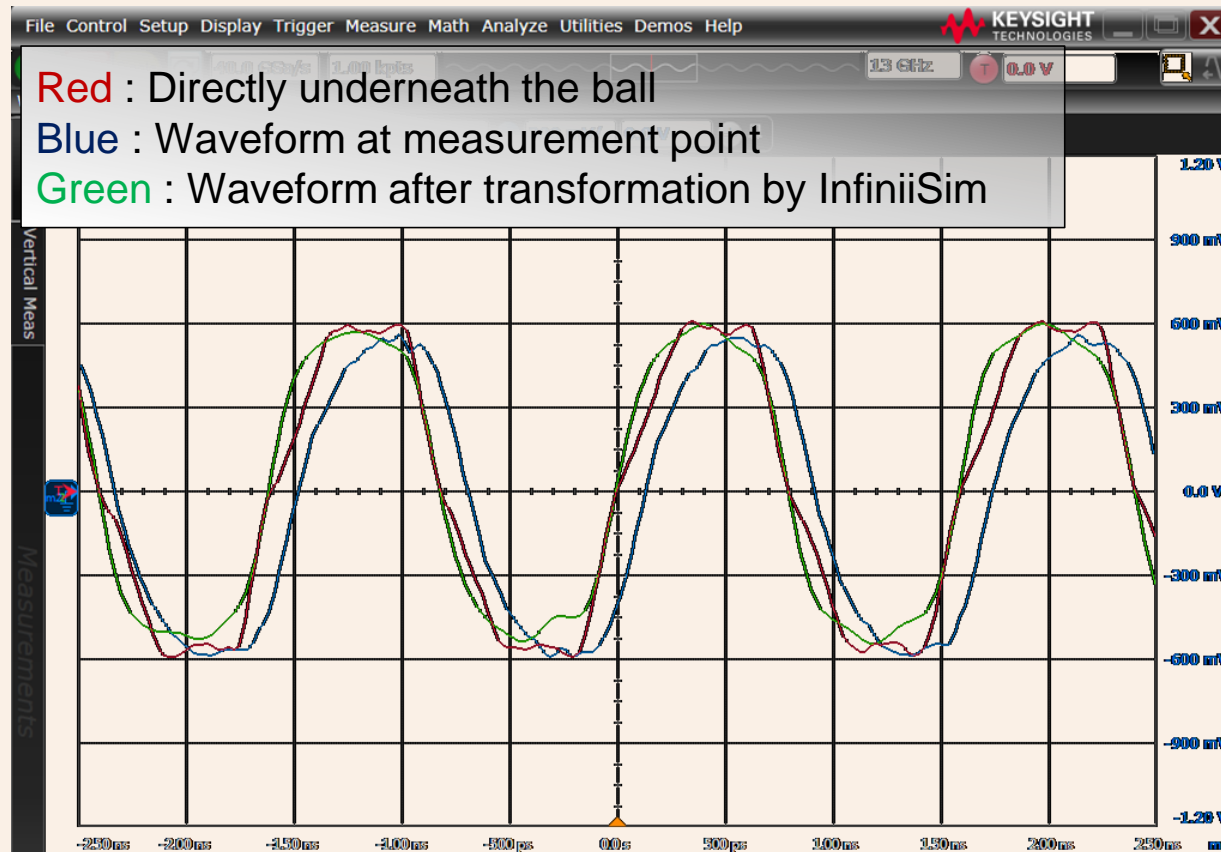
(a),(b) and (c) must be subtracted from measurement waveform to get the actual data of the IC terminal.



Testing procedure & method



DDR clock signal waveform transformed



4) Conclusion & Summary

Conclusion & Summary

1. The signal probe socket can measure blind signal waveform behind of IC package.
2. Blind signal waveform is able to reform by InfiniiSim using S-parameter data of signal probe socket.
3. It bring system engineers significant system performance information detail.
4. It is a new approach for evaluation & analysis in the world.

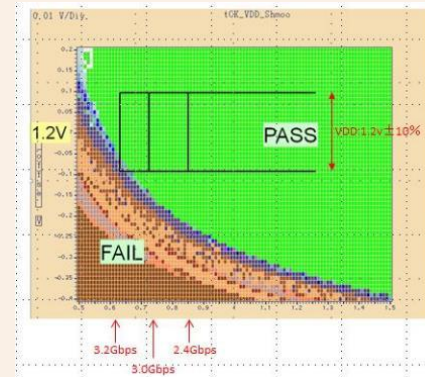
Future works

1. Support high speed **DDR4** memory

Minimize stub

Minimize probe length

4.3mm \Rightarrow 2.6mm



And for 10GHz speed requirement

2. Approach **power integrity** analysis

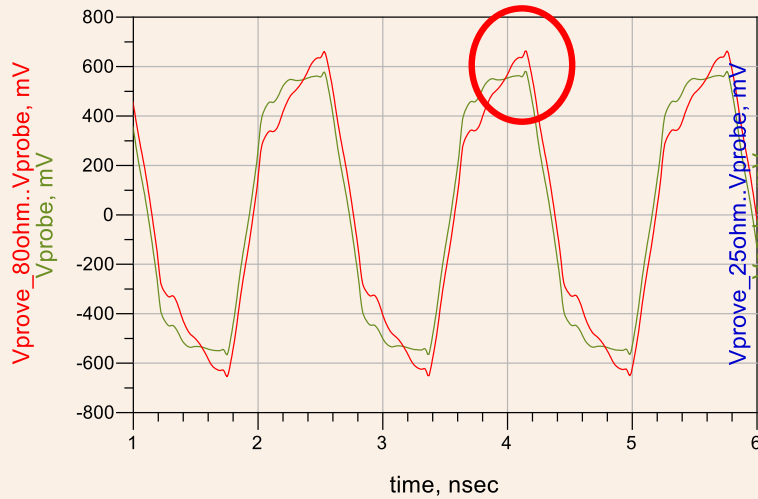
Acknowledgements

Keysight Technologies Japan

Hiroyuki Shimada (MoDech inc)

Appendix

$R = 80 \Omega$



$R = 25 \Omega$

